Introduction to CAD Techniques for Design and Verification

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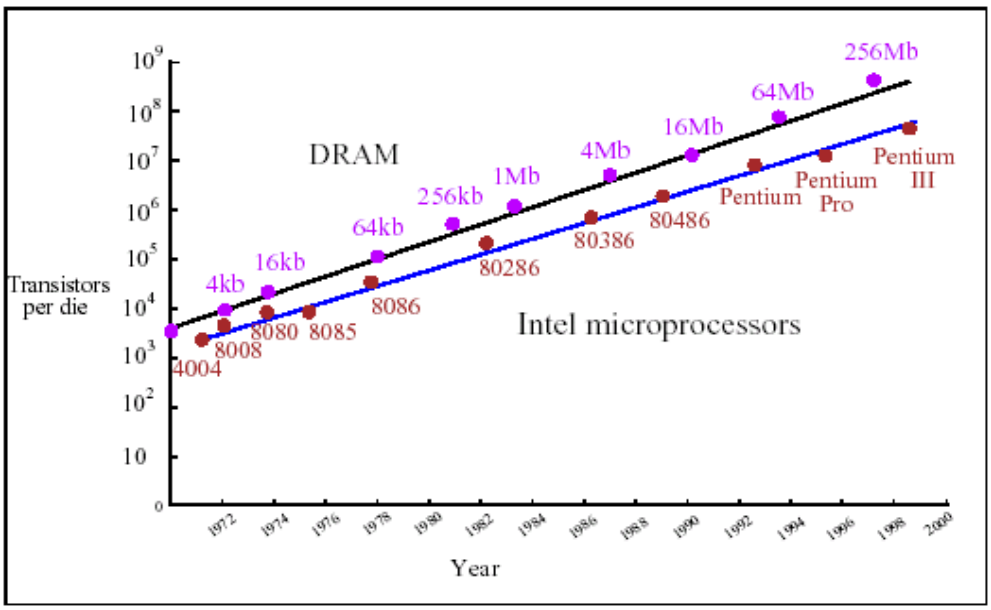
Outline

- Moving to SOC
- CAD in SOC Design
- Solutions for Verification Problems
- Solutions for Integration Problems
- Solutions for DSM Problems

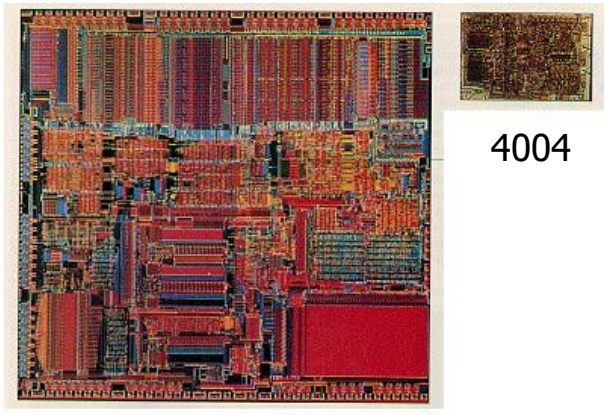
Moore's Law

- Logic capacity doubles per IC per year at regular intervals (1965)
- Logic capacity doubles per IC every 18 months (1975)



The Dies of Intel CPUs

Pentium Pro



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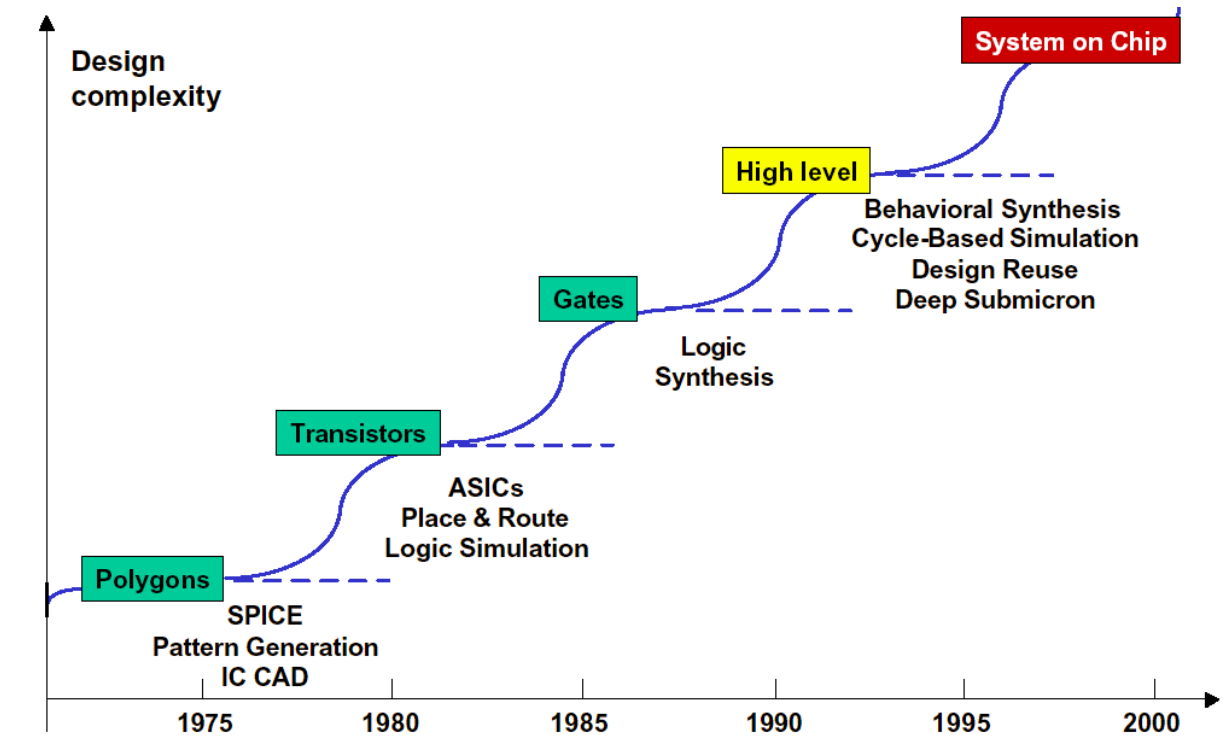
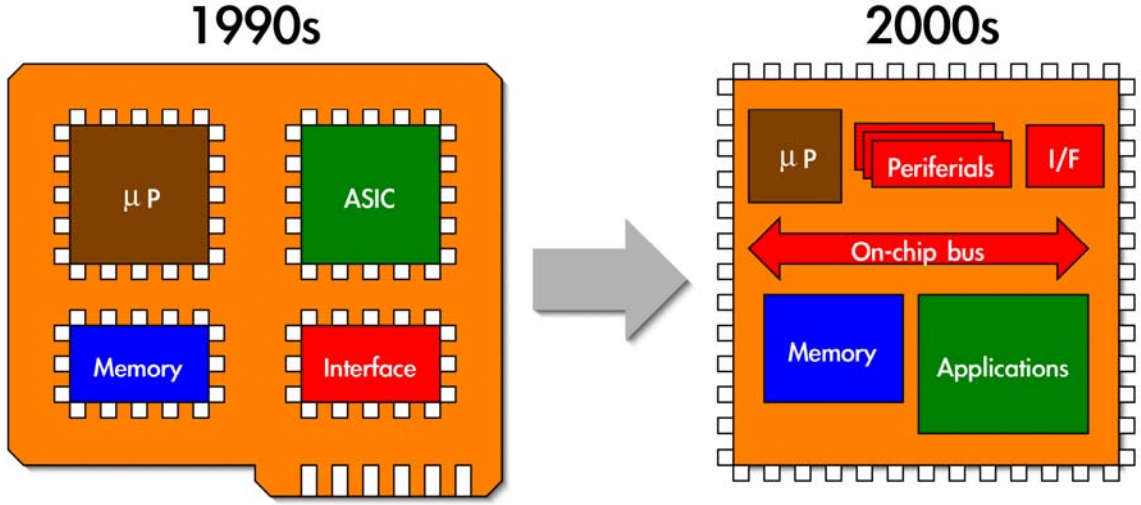
Trends of VLSI Design



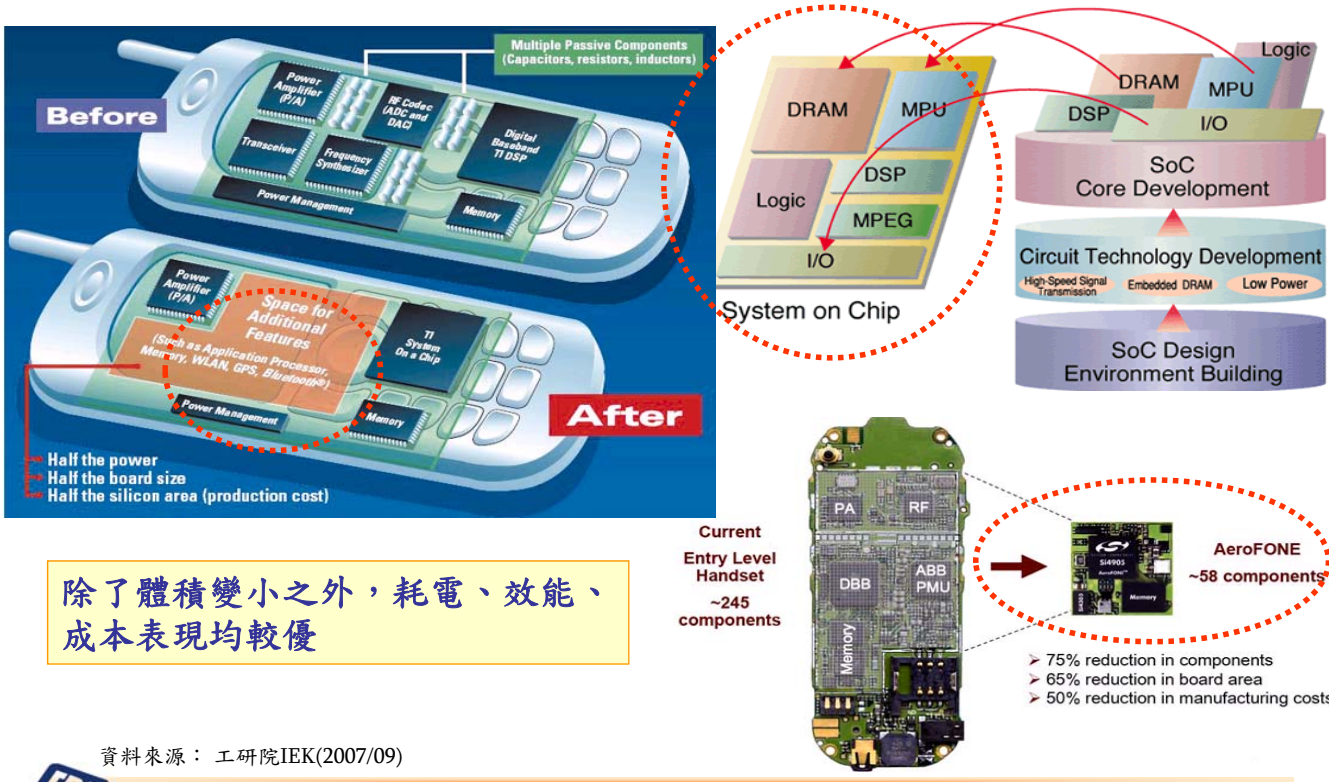
Reference : www.doulos.com

What is SoC?

- System-on-Chip
- An IC that integrates the major functional elements of a complete end-product into a single chip



Why Highly Integrated Circuits?



除了體積變小之外，耗電、效能、成本表現均較優

資料來源： 工研院IEK(2007/09)

SoC Challenges

- Increasing complexity
  - Time-to-market pressure
  - Verification bottleneck
- Integration
  - Hardware v.s. software
  - Digital circuits v.s. analog circuits
  - Testing issues
- Deep submicron effects
  - Timing closure problem
  - Signal integrity problem
  - Reliability problem

Time-to-Market Pressure

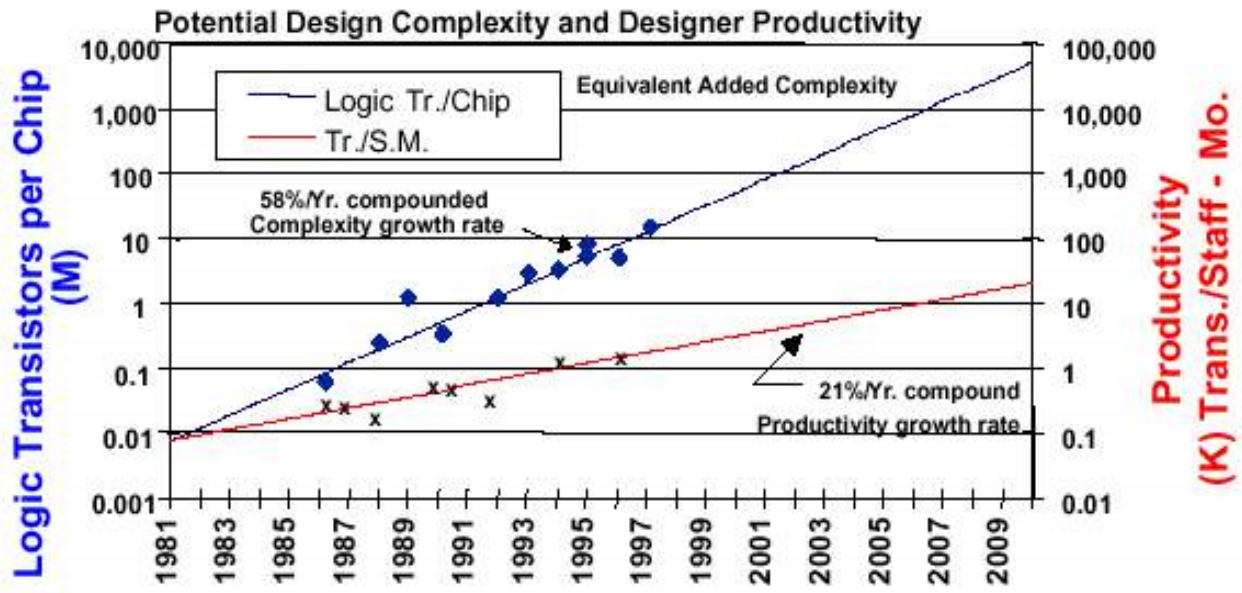
- A lot of pressure from
  - Shorter product lifespan
  - Shrinking design cycles

	1997	1998	1999	2002
Applications	Cellar, PDA, DVD	Set-top boxes, wireless PDA	Internet applications, anything portable	Ubiquitous computing, intelligent, interconnected controllers
Design cycle (month)	18 - 12	12 - 10	10 - 8	8 - 6
Derivative cycle (month)	8 - 6	6 - 4	4 - 2	3 - 2

* Adapted from "Surviving the SOC Revolution."

Productivity Gap

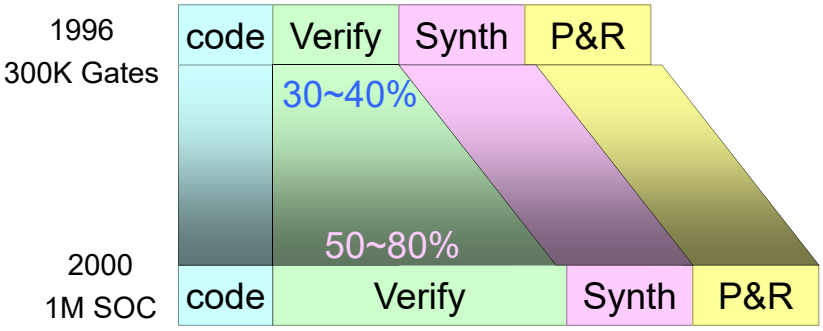
- We do need more productivity !! → **CAD**



Source : ITRS Roadmap 1999 Edition, SIA.

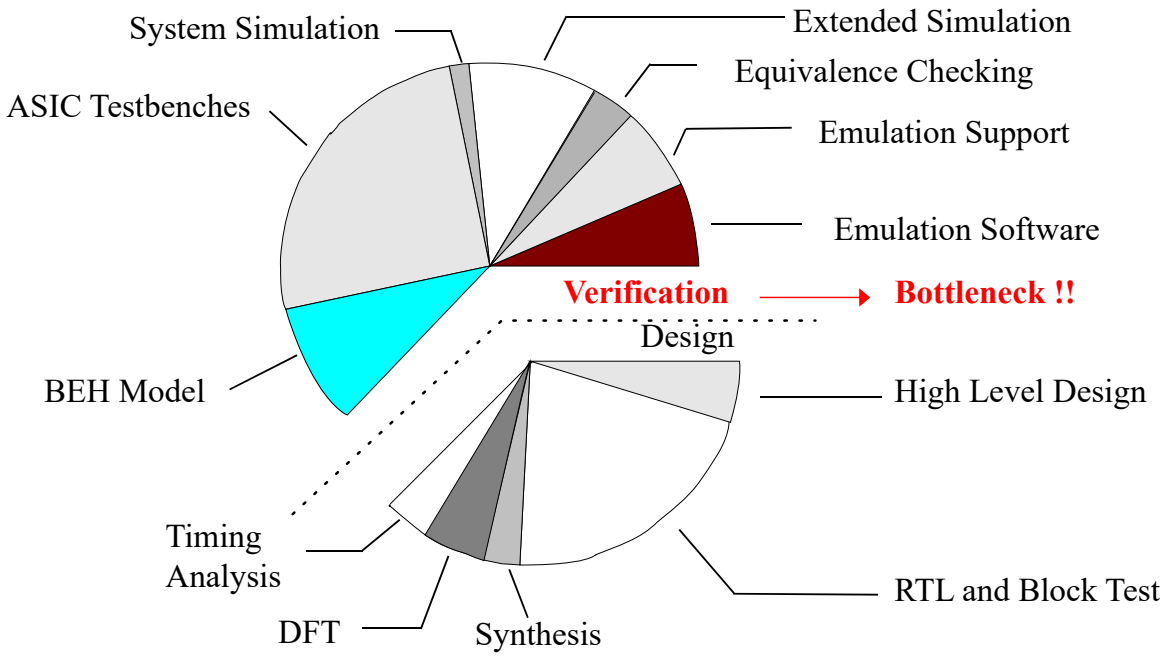
Verification Bottleneck

- Verification becomes the major bottleneck of the modern design flows
  - From 30%-40% to 50%-80%



- An effective verification methodology is also highly desirable

An Industrial Example



Source : "Functional Verification on Large ASICs" by Adrian Evans, etc., 35th DAC, June 1998.

SoC Challenges

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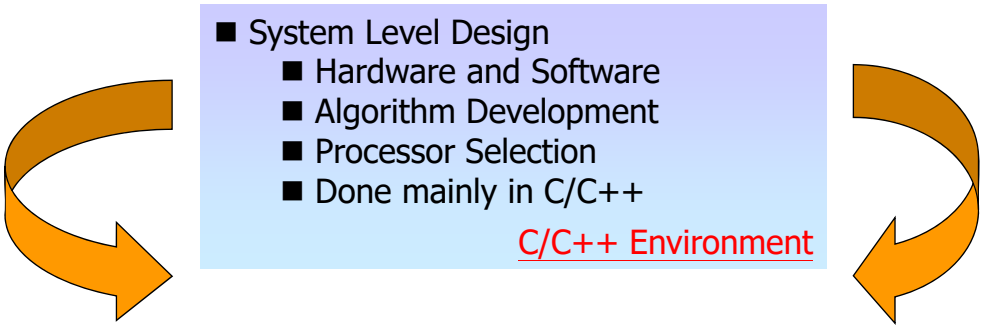
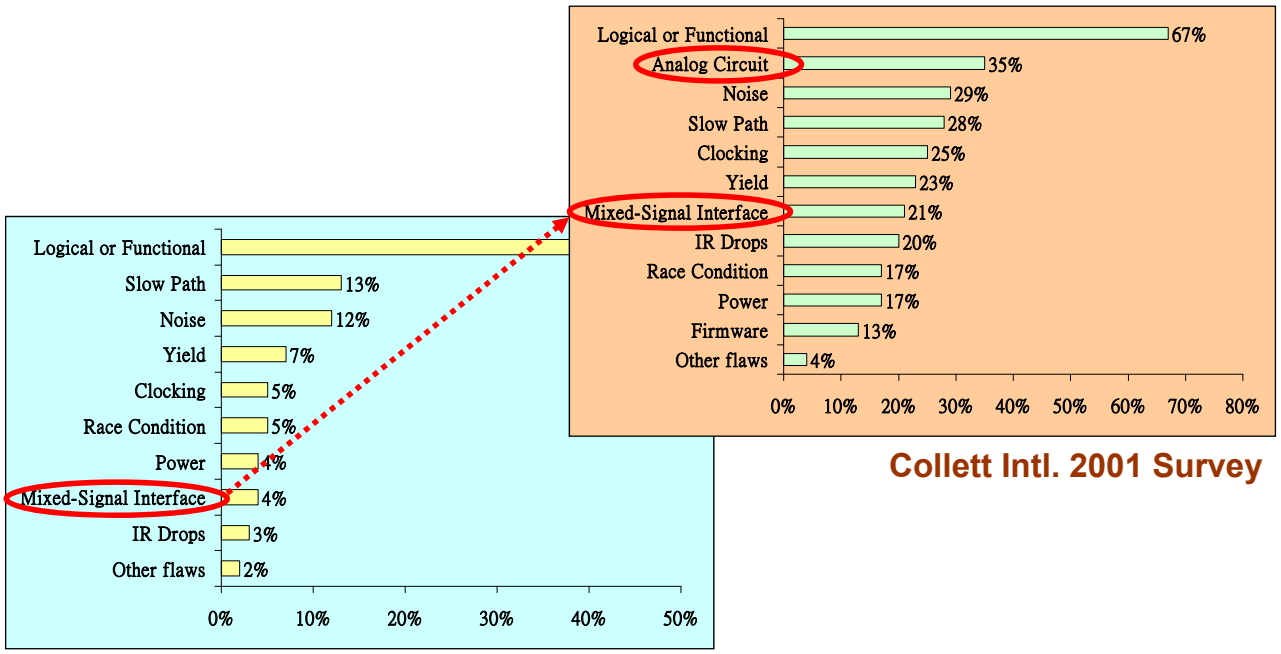
HW/SW Integration

- Integrating HW/SW at the final step may require high cost to fix inconsistency problems



Reference : Synopsys

Mixed Signals in SoC



Collett Intl. 2000 Survey

Collett Intl. 2001 Survey

Challenges for MS Designs

- Design challenges
  - Chip-level simulation takes too much time
  - Design budgets are not distributed in a well-defined manner
  - Too much time is spent on low-level iterations
  - Design is not completely systematic
  - There is limited or no use of HDL
- Solutions:
  - Use a systematic, top-down design approach to capture design intent
  - Develop some tools for rapid targeting of different design technologies

SoC Testing Challenges

- Distributed design and test
  - Core provider does not know the target environment
  - System integrator is responsible for manufacturing testing
- Test access
  - Difficulties to access deeply embedded cores
  - Bandwidth, I/O pin count limitations
- Test optimization
  - Minimizing test cost while satisfying constraints such as power, resources, coverage, etc.

SoC Challenges

- Increasing complexity
  - Time-to-market pressure
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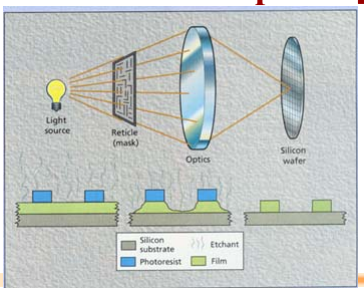
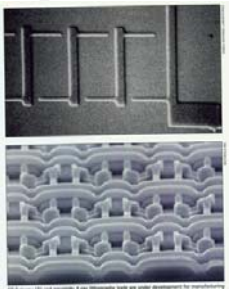
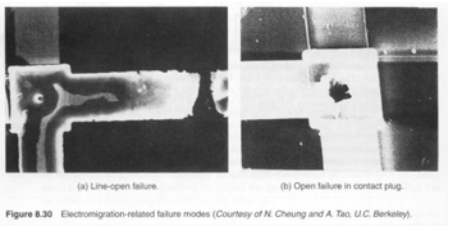
Nanometer Design Challenges

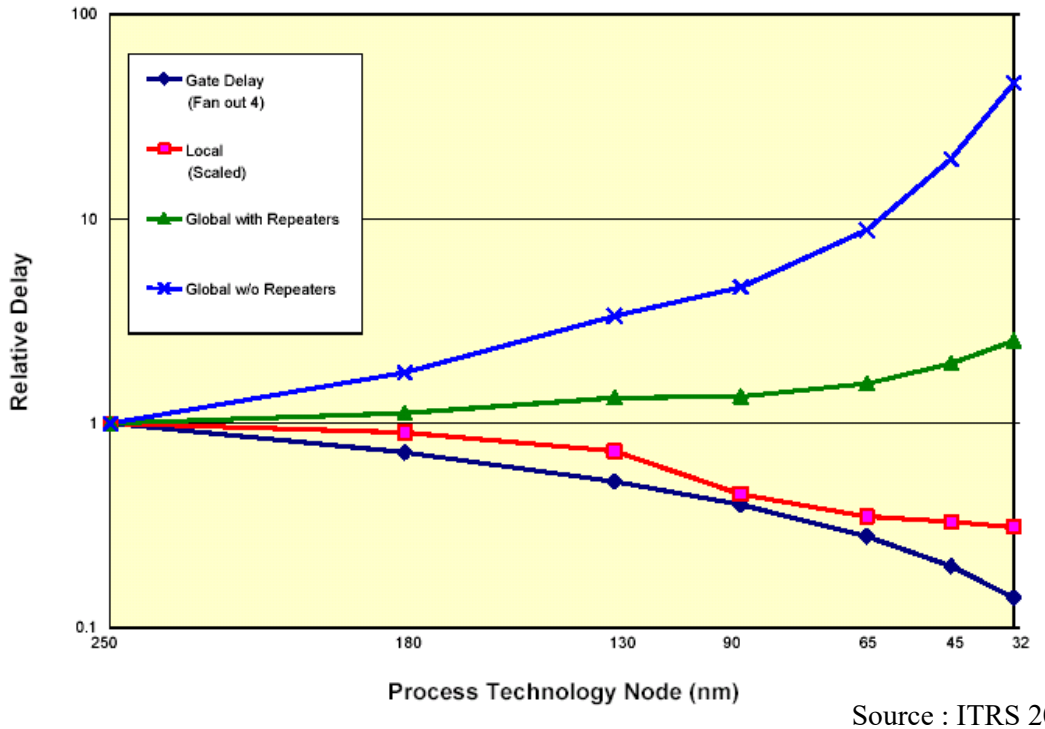
- In 2005, feature size ≈ 0.1 μm, μP frequency ≈ 3.5 GHz, die size ≈ 520 mm^2, μP transistor count per chip ≈ 200M, wiring level ≈ 8 layers, supply voltage ≈ 1 V, power consumption ≈ 160 W.
  - **Feature size ↓ → sub-wavelength lithography (impacts of process variation)? noise? wire coupling? reliability?**
  - **Frequency ↑, dimension ↑ → interconnect delay? electromagnetic field effects? timing closure?**
  - **Chip complexity ↑ → large-scale system design methodology?**
  - **Supply voltage ↓ → signal integrity (noise, IR drop, etc)?**
  - **Wiring level ↑ → manufacturability? 3D layout?**
  - **Power consumption ↑ → power & thermal issues?**







Wiring Delay vs. Feature Size



Source : ITRS 2001

Timing Closure Problem

- Wire delay starts to dominate total delay in DSM process
  - Cannot be ignored as taught in digital design course
- Only statistical wire delay model can be used at design phase
  - Lack of physical information about wire length
- Incorrect estimations require long iterations to meeting timing
  - Design schedule will be seriously delayed !!

Path name	Pre-layout delay	Post-layout delay
P1	21.72	40.92 (+88.4%)
P2	6.65	7.81 (+17.4%)
P3	11.14	10.43 (-6.4%)
P4	5.03	5.44 (+8.15%)
P5	6.35	13.21 (+108.0%)
P6	6.42	13.20 (+105.6%)

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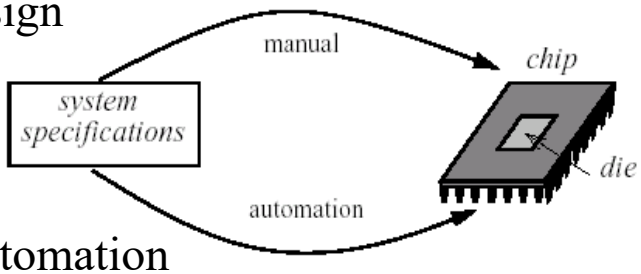
What is CAD ?

- CAD = Computer-Aided Design
  - Exist everywhere in the whole design flow
  - Important but invisible

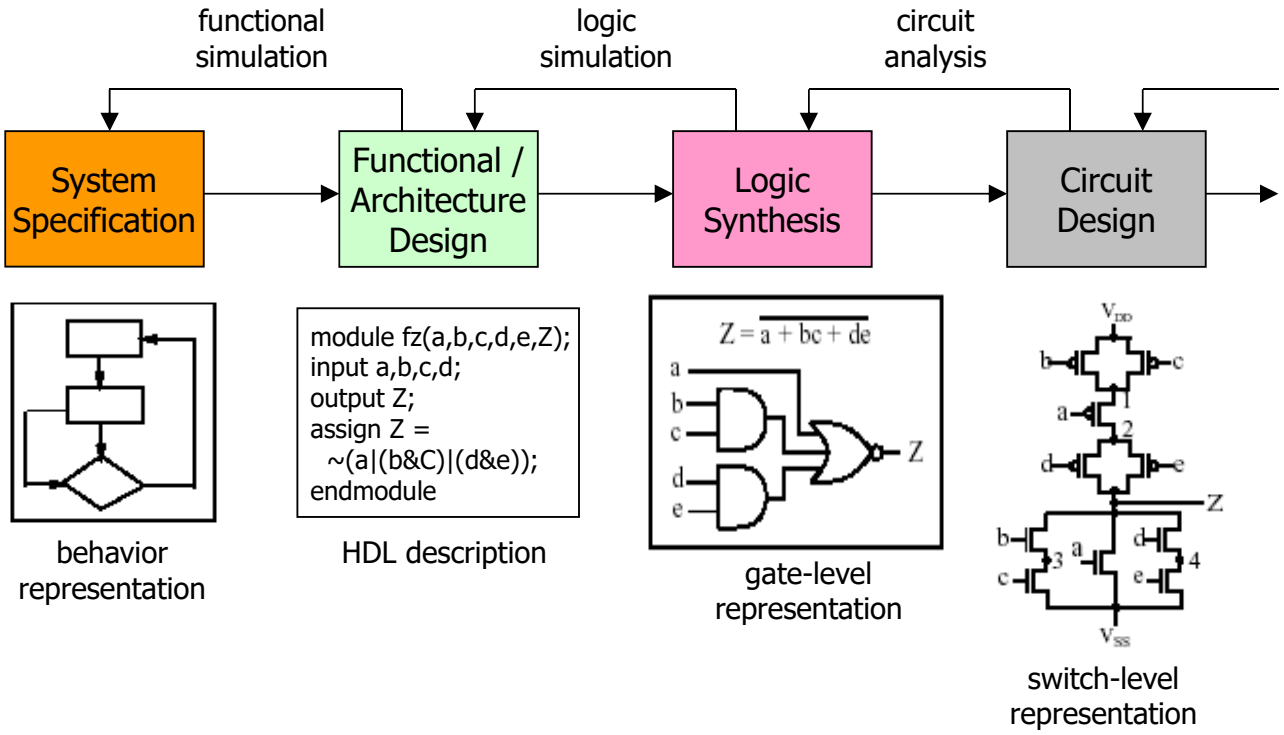


- EDA = Electronic Design Automation
  - CAD for electronic industry
- Typically, more than 50% design time is elapsed on running CAD tools
  - Meet the time to market → faster implementation
  - Reduce costs → less engineers
  - Higher quality → fewer bugs
  - Managing the complexity → larger designs

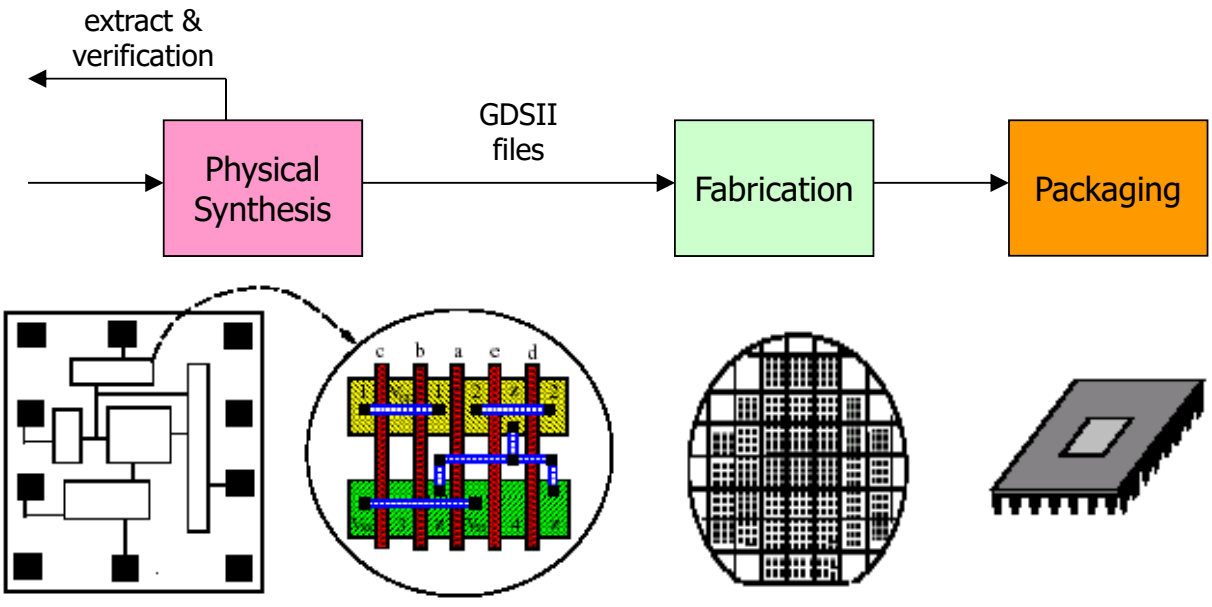
Human vs. Computer

- Computation time
  - Human: slow
  - Computer: fast
- Correctness of results
  - Human: not guaranteed
  - Computer: always correct
- Working hours
  - Human: 8hrs / day
  - Computer: 24hrs / day
- And more and more advantages …

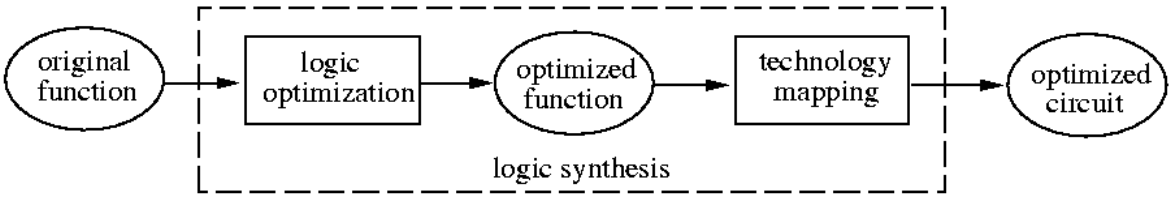
Typical VLSI Design Flow



Typical VLSI Design Flow



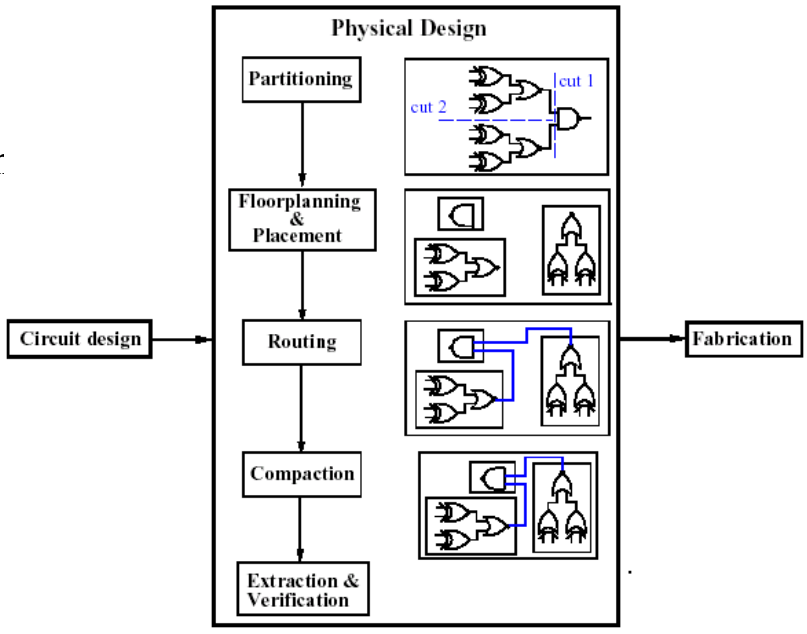
Logic Design/Synthesis



- **Logic synthesis** programs transform Boolean expressions into logic gate networks in a particular library.
  - Optimization goals: minimize area, delay, power, etc
- **Technology-independent** optimization: logic optimization
  - Optimizes Boolean expression equivalent.
- **Technology-dependent** optimization: **technology mapping/library binding**
  - Maps Boolean expressions into a particular cell library.

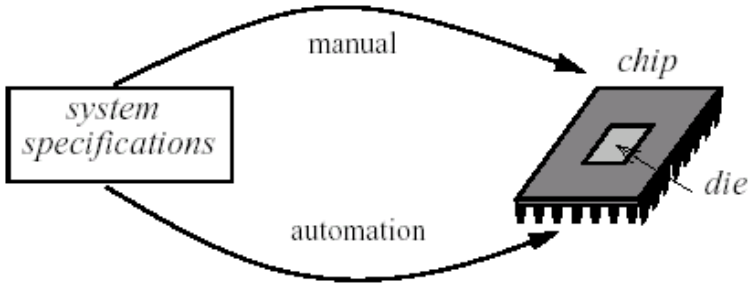
Physical Design Flow

- Physical design cycle:
  1. Logic partitioning
  2. Floorplanning, placement, and pir assignment
  3. Routing (global and detailed)
  4. Compaction
  5. RLC extraction & verification



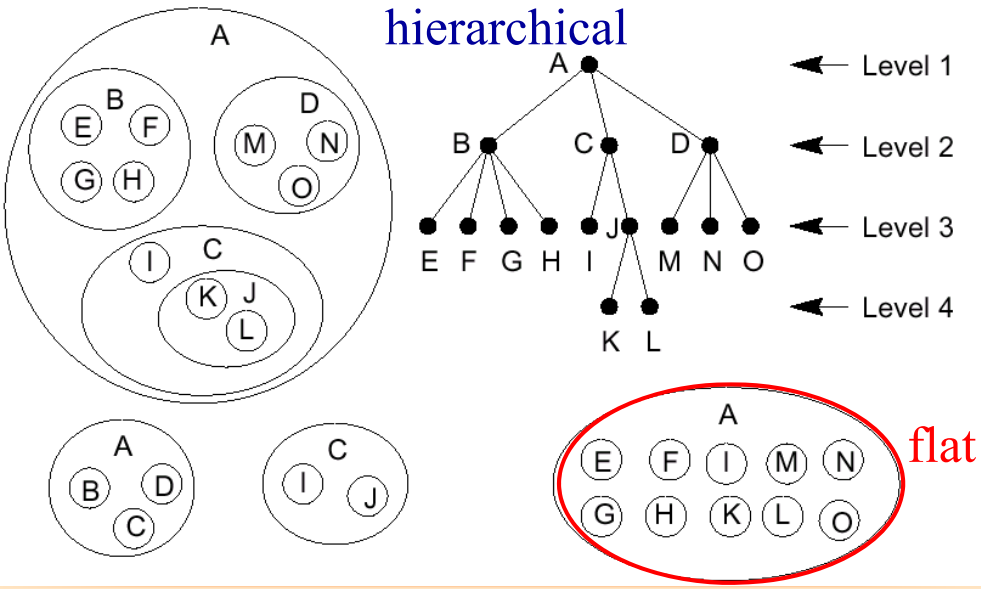
VLSI Design Considerations

- Several conflicting considerations
  - **Design complexity**: large number of devices/transistors
  - **Cost**: die area, packing, testing, etc.
  - **Performance**: optimization requirements for high performance
  - **Time-to-market**: about 15% gain for early birds
  - Others: power, noise, testability, reliability, … etc.
- Keys: hierarchical design, abstraction, design automation



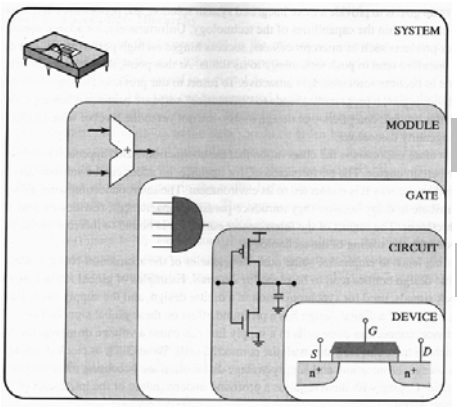
Hierarchical Design

- *Hierarchy:* something is composed of simpler things.
- Design cannot be done in one step ⇒ partition the design hierarchically



Abstraction

- ***Abstraction:*** when looking at a certain level, you don't need to know all details of the lower levels.



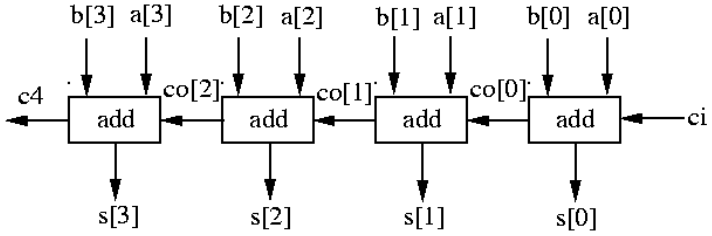
- Design domains:
  - Behavioral: functionality of components
  - Structural: connectivity between components
  - Physical: layout description
- Each design domain has its own hierarchy.

Three Design Views

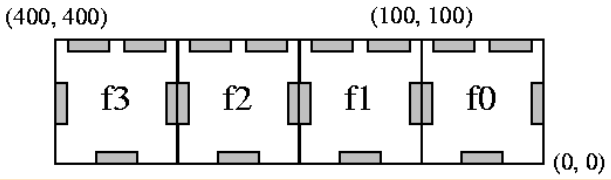
Behavior

```
Module add4 (s, c4, ci, a, b);
   input [3:0] a, b;
   input ci;
   output [3:0] s;
   output c4;
  assign {c4,s} = a + b + ci;
endmodule
```

Structural

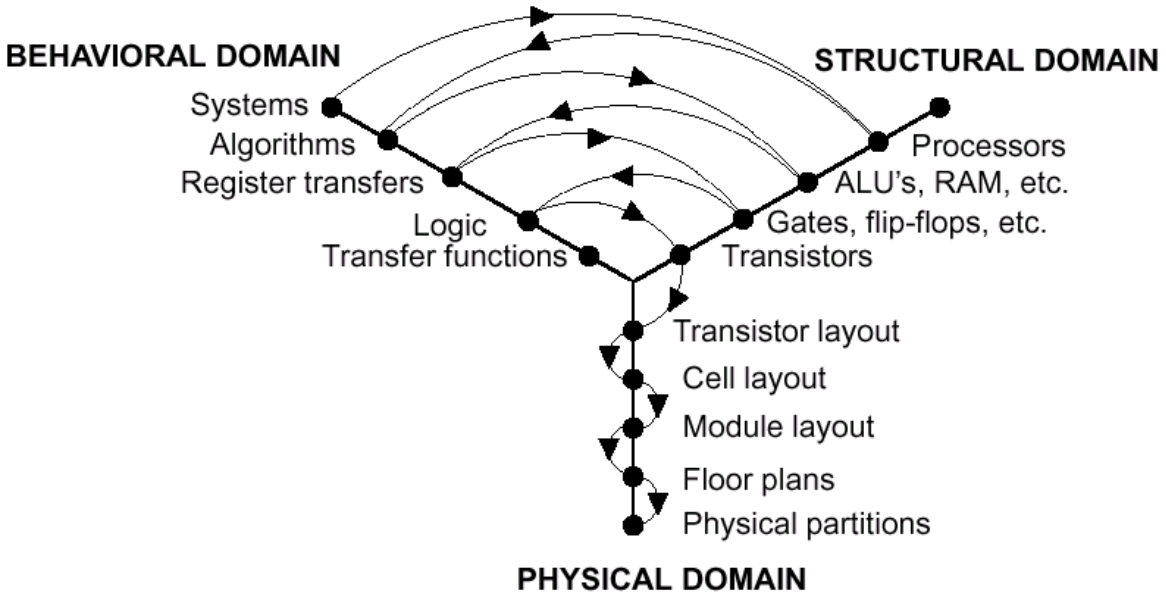


Physical



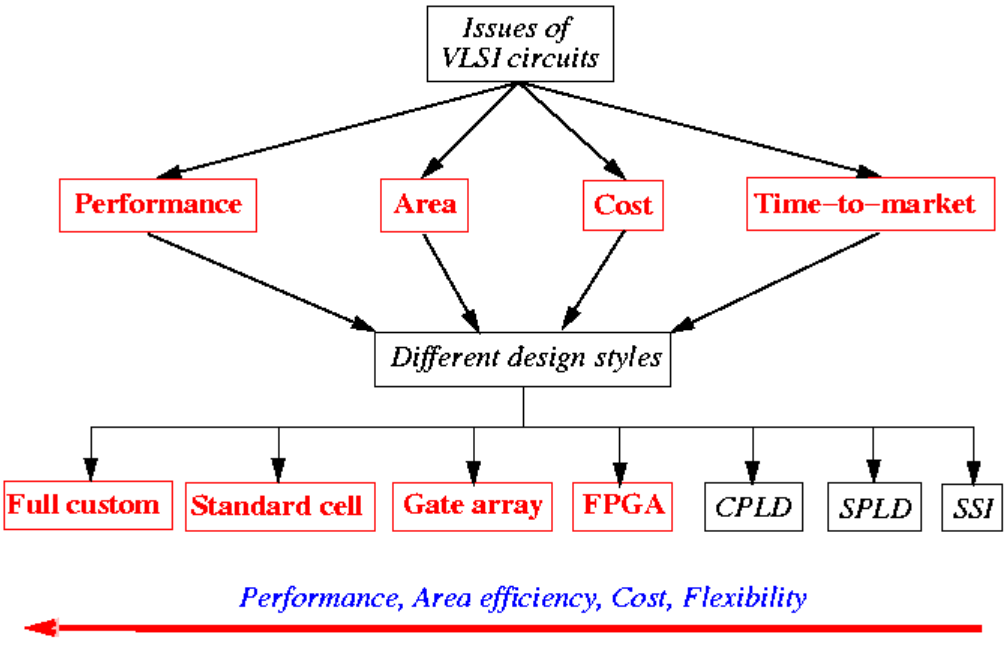
Top-Down Structural Design

- Also known as the Gajski's Y chart

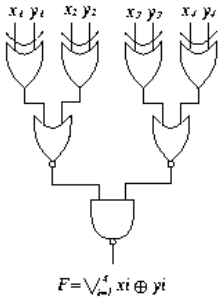


Design Styles

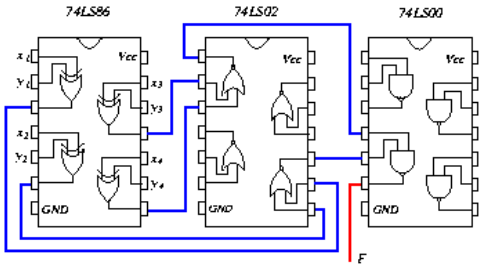
- Specific design styles shall require specific EDA tools



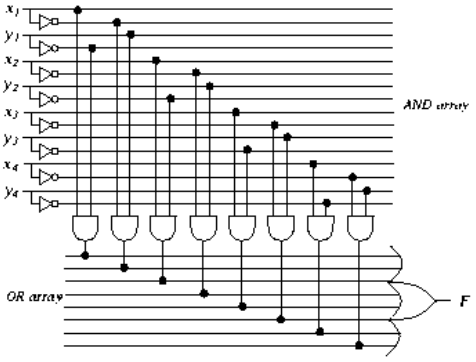
SSI/SPLD Design Style



(a) 4–bit comparator.



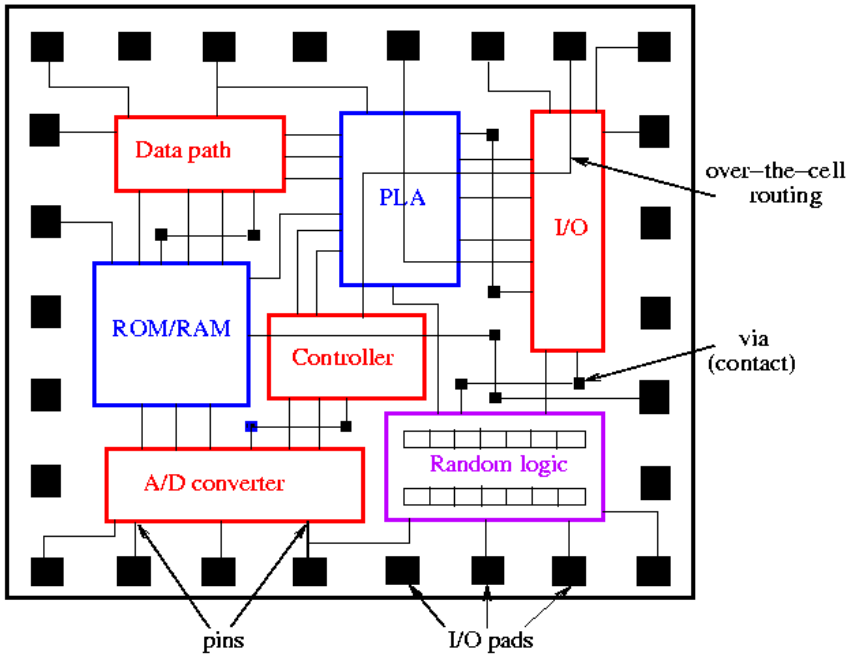
(b) SSI implementation.



(c) SPLD (PLA) implementation.

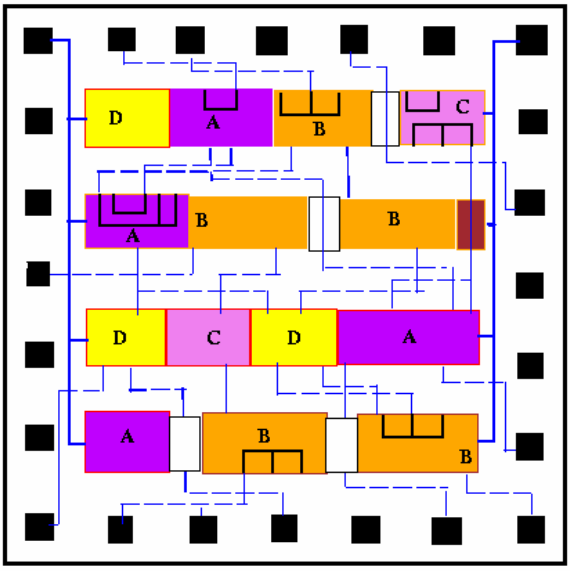
Full Custom Design Style

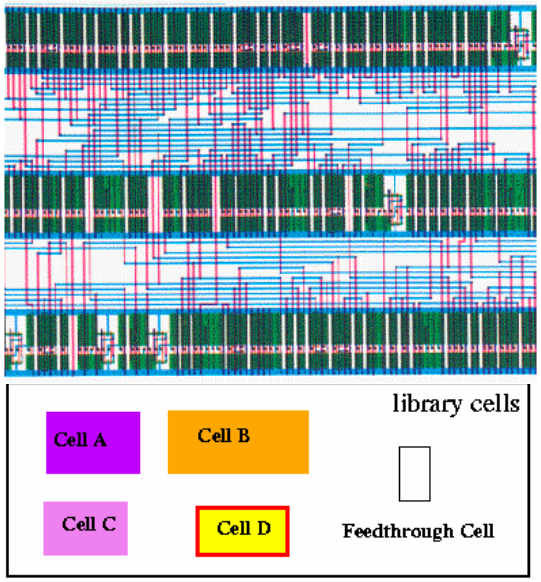
- Designers can control the shape of all mask patterns.
- Designers can specify the design up to the level of individual transistors.



Standard Cell Design Style

- Select pre-designed cells (of same height) to implement logic
- Characterize and store cells in library

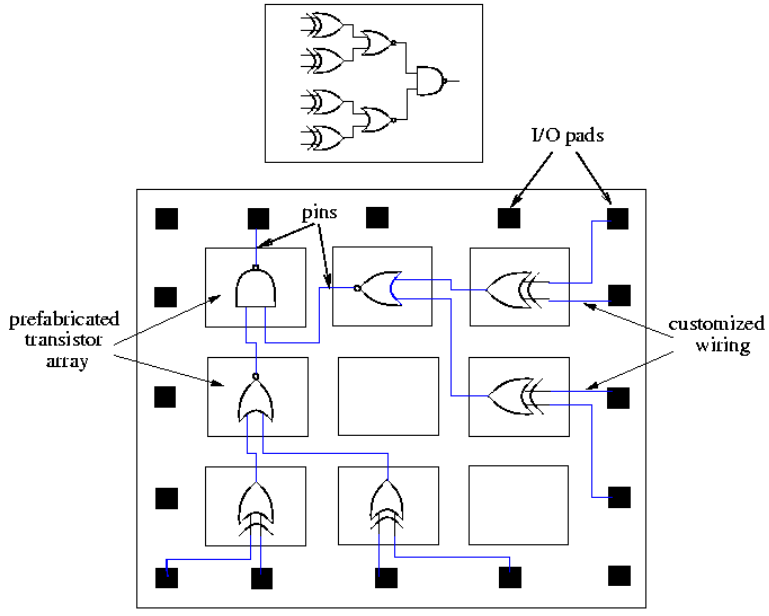




Courtesy Newton/Pister, UC-Berkeley

Gate Array Design Style

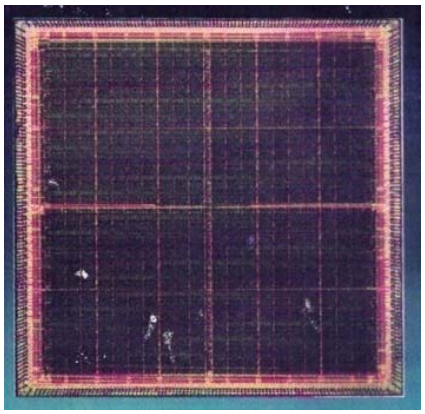
- Prefabricates a transistor array
- Needs wiring customization to implement logic

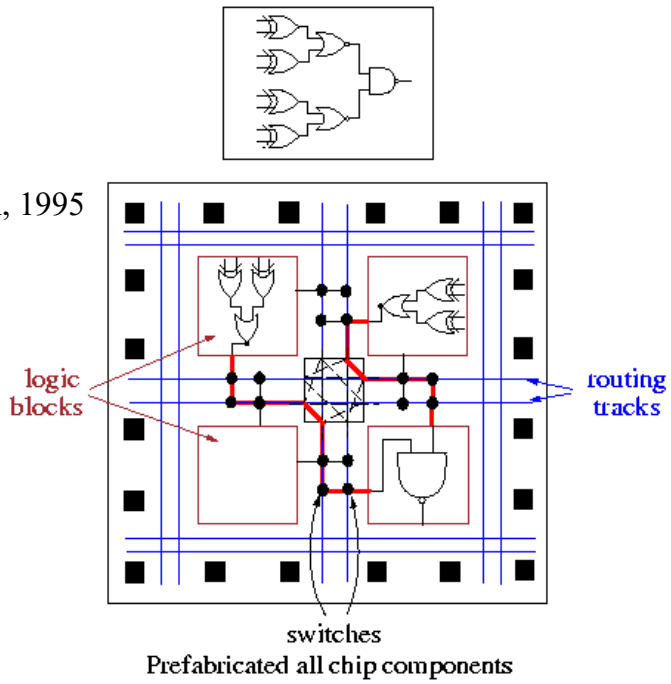


FPGA Design Style

- Logic and interconnects are both prefabricated.
- Illustrated by a symmetric array-based FPGA
- Another example:

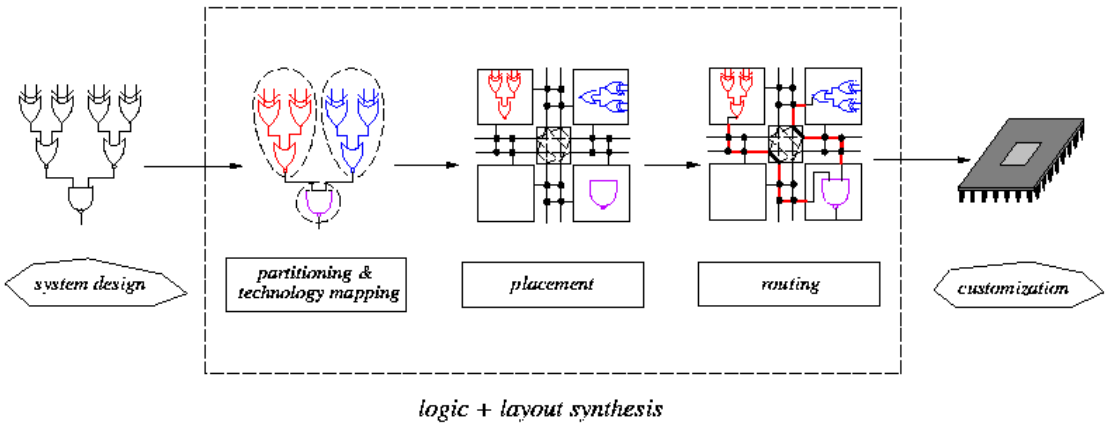
  Lucent Technologies 15K ORCA FPGA, 1995





FPGA Design Process

- Illustrated by a symmetric array-based FPGA
- No fabrication is needed



Comparisons of Design Styles

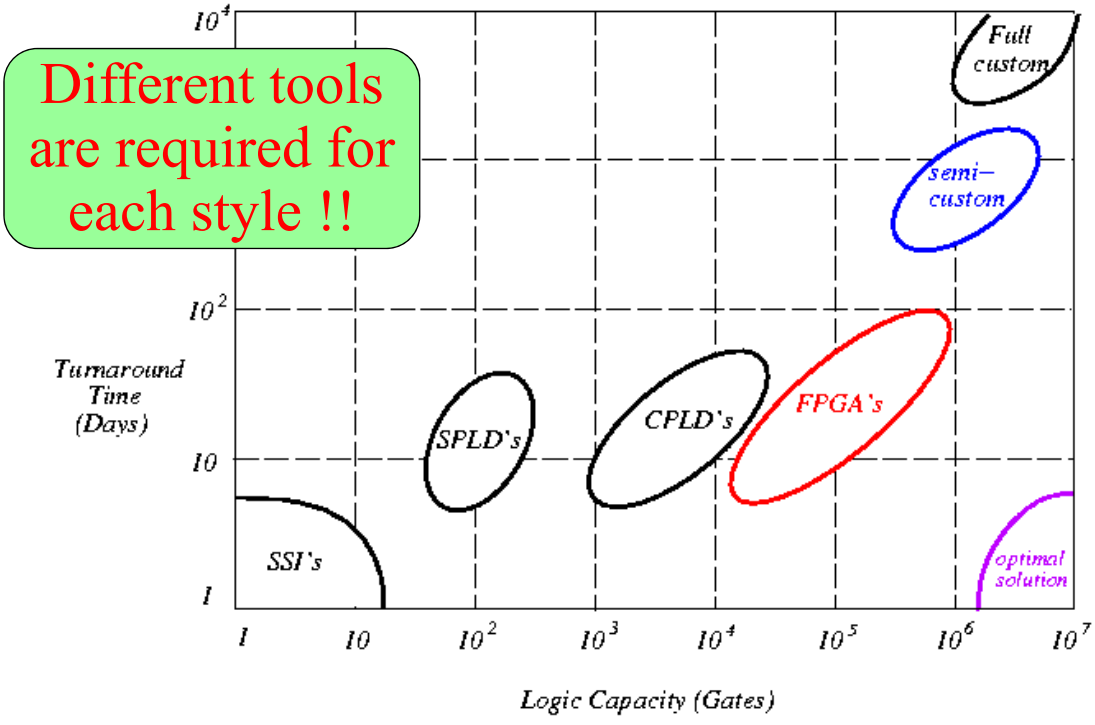
	Full custom	Standard cell	Gate array	FPGA	SPLD
Cell size	variable	fixed height*	fixed	fixed	fixed
Cell type	variable	variable	fixed	programmable	programmable
Cell placement	variable	in row	fixed	fixed	fixed
Interconnections	variable	variable	variable	programmable	programmable

* Uneven height cells are also used.

	Full custom	Standard cell	Gate array	FPGA	SPLD
Fabrication time	− − −	− −	+	+++	++
Packing density	+++	++	+	− −	− − −
Unit cost in large quantity	+++	++	+	− −	−
Unit cost in small quantity	− − −	− −	+	+++	++
Easy design and simulation	− − −	− −	−	++	+
Easy design change	− − −	− −	−	++	++
Accuracy of timing simulation	−	−	−	+	++
Chip speed	+++	++	+	−	−−

+ desirable; − not desirable

Design Style Trade-Offs



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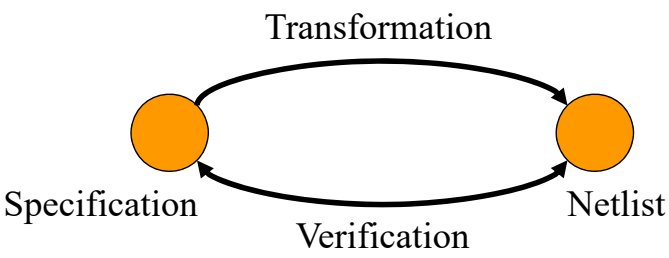
What is Verification ?

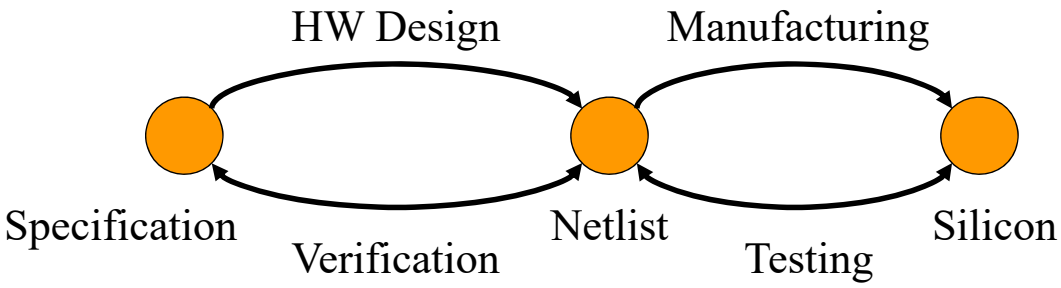
- A process used to demonstrate the functional correctness of a design
- To making sure that you are indeed implementing what you want
- To ensure that the result of some transformation is as expected



Source : "Writing Test Benches – Functional Verification of HDL Models" by Janick Bergeron, KAP, 2000.

Testing v.s. Verification

- Testing verifies manufacturing
  - Verify that the design was manufactured correctly

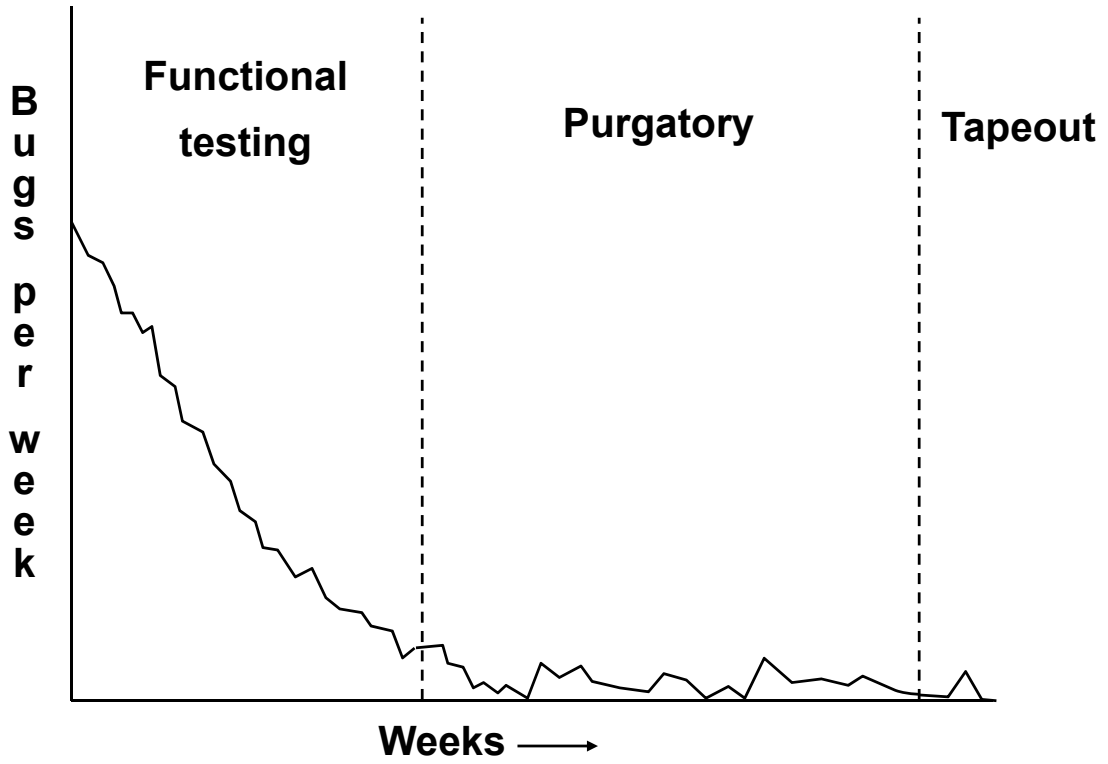


Source : "Writing Test Benches – Functional Verification of HDL Models" by Janick Bergeron, KAP, 2000.

When is Verification Complete ?

- Some answers from real designers:
  - When we run out of time or money
  - When we need to ship the product
  - When we have exercised each line of the HDL code
  - When we have tested for a week and not found a new bug
  - ***We have no idea!!***
- Designs are often too complex to ensure full functional coverage
  - The number of possible vectors greatly exceeds the time available for test

Typical Verification Experience



The Famous Pentium Bug

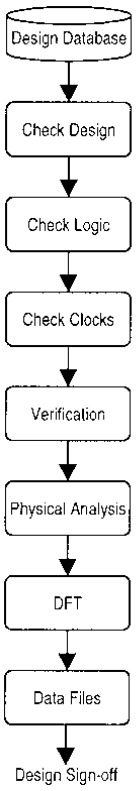
- Summary of the Pentium division bug
  - Pentium was Intel's mainstream microprocessor
    - 3.3 Million transistors
  - Early versions all had error in floating point division hardware
    - 5 missing transistors, fixed with change to single mask
  - Disclosed largely via Internet
  - Intel ultimately offered replacements to everyone
    - $475 Million charge from 4Q94 revenue

Why Did not Intel Discover it ?

- Standard steps in verifying design
  - Simulate many cases on high-level software model
  - Simulate/emulate final logic design
    - Hardware emulators costing $Millions
    - Run complete chip model at ~ 100Hz (< 10^{-6} X real time)
  - Run tests on initial production chips
    - Feasible to run billions of tests
    - Should have caught error here
  - 1 trillion (10^{12}) test vectors for Pentium chip
- Observations
  - Hard to test all aspects of such a complex system

Design Sign-off

- Sign-off is the final step in the design process
- It determines whether the design is ready to be taped out for fabrication
- No corrections can be made after this step
- The design team needs to be confident that the design is 100% correct
  - Many items need to be checked
- Many verification tools are involved at each step in the sign-off flow



Ref : "System-on-a-chip Verification – Methodology and Techniques" by P. Rashinkar, etc., KAP, 2001.

Outline

- Moving to SOC
- CAD in SOC Design
- Solutions for Verification Problems
- Solutions for Integration Problems
  - Hardware v.s. software
  - Digital circuits v.s. analog circuits
- Solutions for DSM Problems

Prototyping

- Verify designs using real hardware
  - FPGA, emulator
- Better throughput in handling complex designs
- Software-driven verification
  - Verify SW using HW
- Interfaced with real HW components
- May have a little performance degradation
- May have capacity limitation
- Poor debugging capability
- High cost to fix design problems

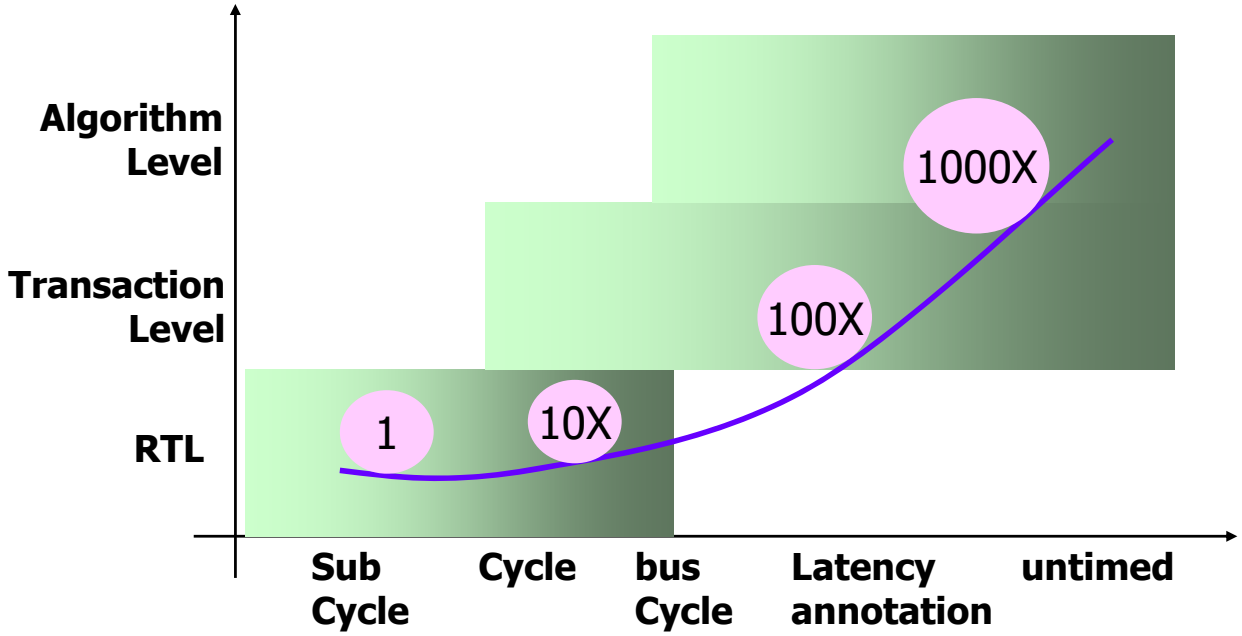
Limited Production

- Even after robust verification process and prototyping, it's still not guaranteed to be bug-free
- Engineering samples
- A limited production for new macro is necessary
  - 1 to 4 customers
  - Small volume
  - Reducing the risk of supporting problems
- Same as real cases but more ***expensive***
- Only used as the final check before mass production

HW/SW Co-Simulation

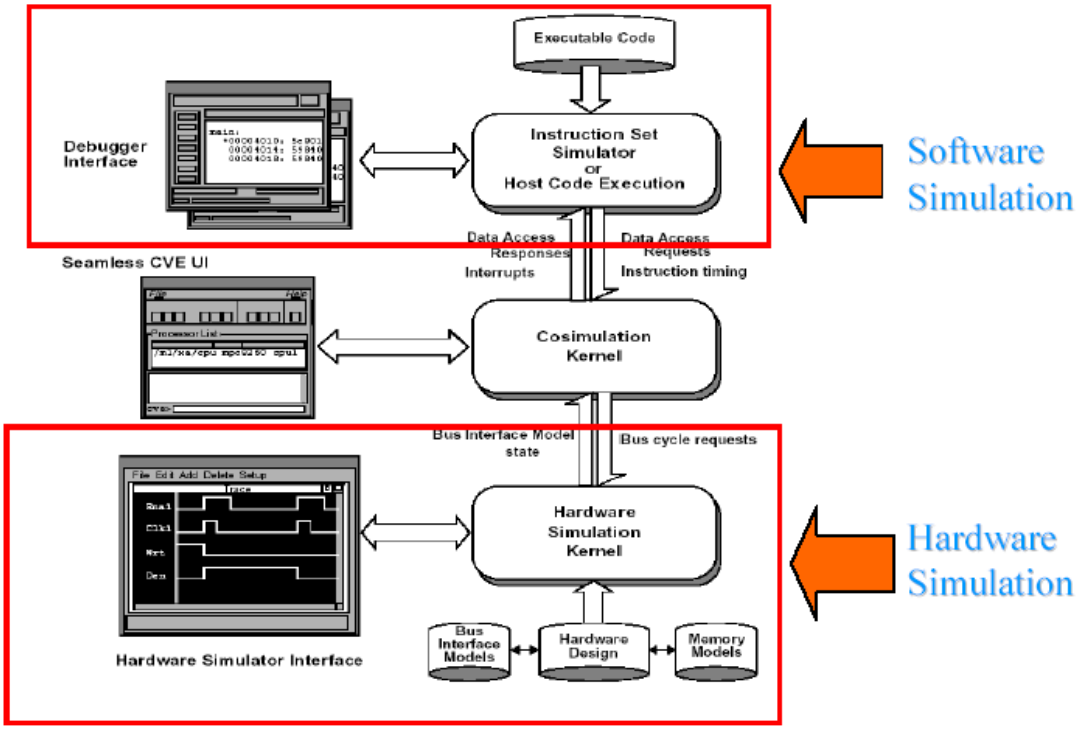
- Couple a software execution environment with a hardware simulator
- Simulate the system at higher levels
  - Software normally executed on an **Instruction Set Simulator** (ISS)
  - A **Bus Interface Model** (BIM) converts software operations into detailed pin operations
- Allows earlier system integration
- Start software development 6 months earlier
- Provide a significant performance improvement for system verification
  - Simulate 100x~1000x faster than RTL

Verification Speed



Reference : Synopsys

Many Available Tools for Co-Sim.



Reference : Mentor Graphics

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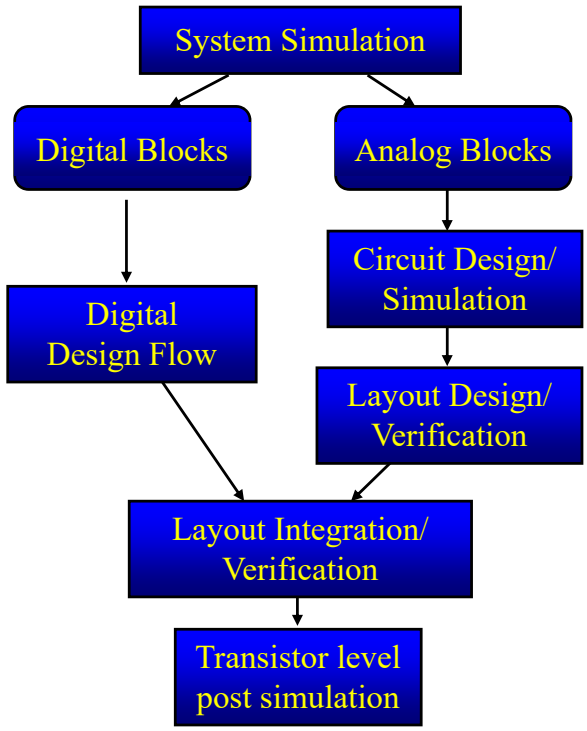
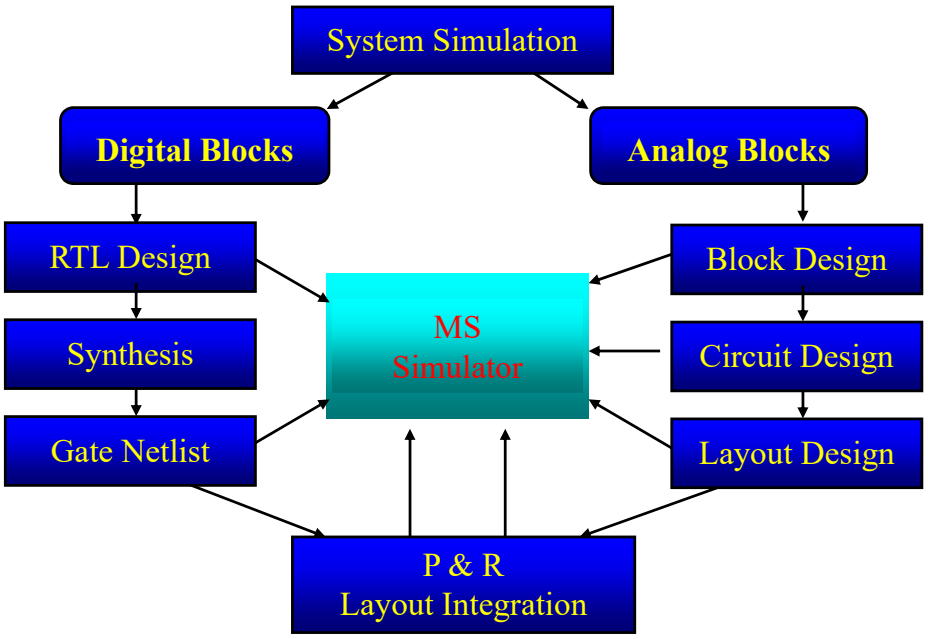
Conventional MS Design Approach



- Design and simulate digital and analog circuits separately
  - May miss the effects between each other
- Can perform co-simulation at transistor level only
  - High complexity
  - Too slow

Top-Down MS Design Flow

- Starting from **behavioral models**
  - Can check whole system behavior in advance



Behavioral Modeling

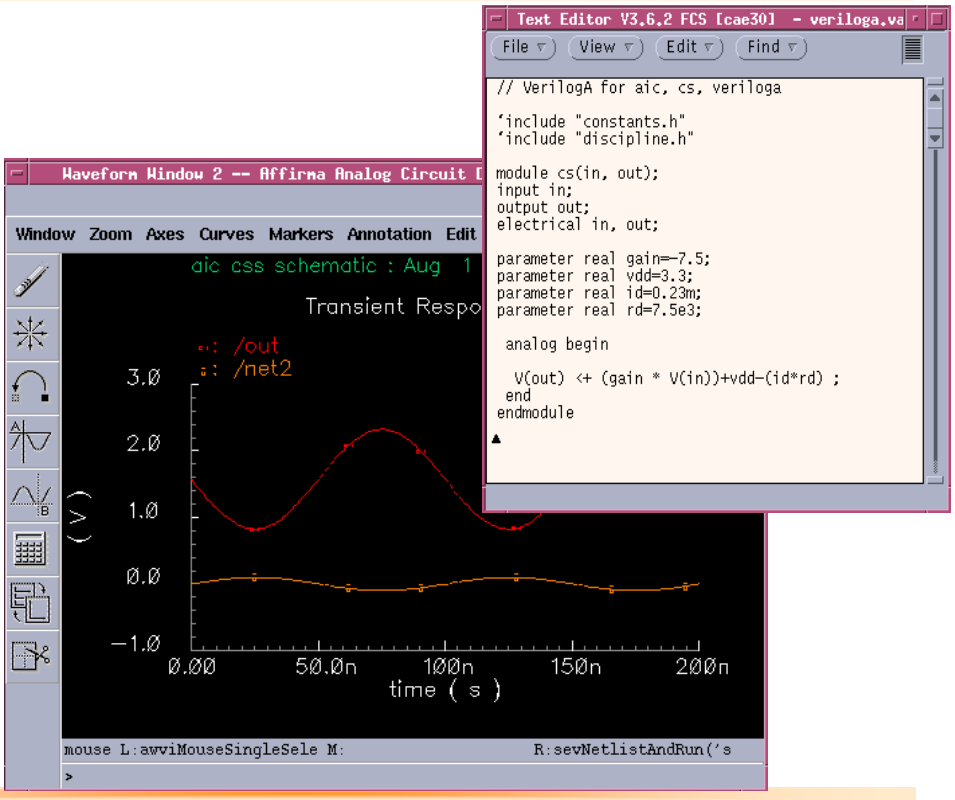
- A mathematical model written in **Hardware Description Language**
  - Verilog-A
  - Verilog-AMS
  - VHDL-A
  - VHDL-AMS
  - ……
- Emulate circuit block functionality by sensing and responding to circuit conditions

Why Behavioral Simulation ?

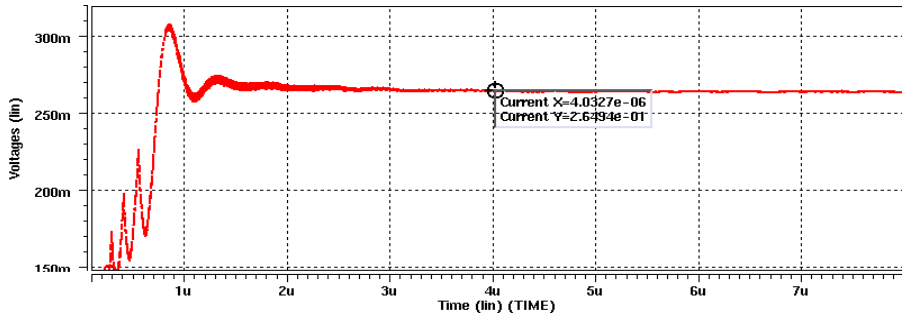
- **Faster** simulation
- Can verify circuit blocks at **behavioral level**
- Allow **system simulation** with pin-accurate block models
  - Easier to verify the system integration
- Digital blocks can also be simulated together in a mixed-signal environment
- Whole chip simulation becomes feasible
- Have to change the original methodology of analog designers
  - Hard !!

Available Simulation Environment

- Cadence
- Antrim
- Mentor
- Synopsys
- ……

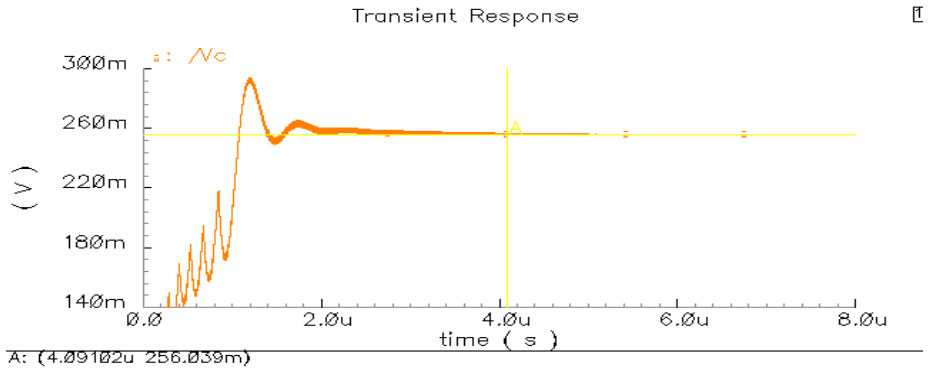


Waveform of PLL Locking



HSpice

Lock time:
4.03 us
Lock voltage:
0.265 v
Simulation time:
22405 sec



Verilog-A

Lock time:
4.09 us
Lock voltage:
0.256 v
Simulation time:
336 sec

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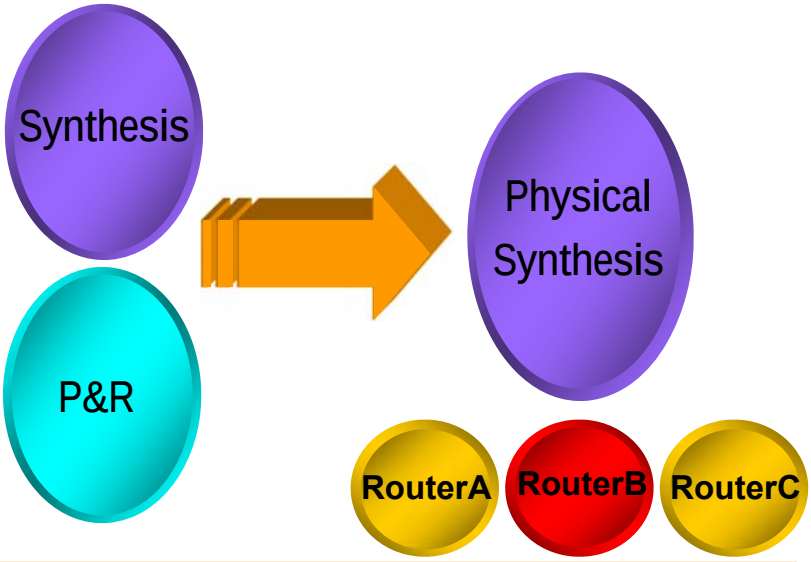
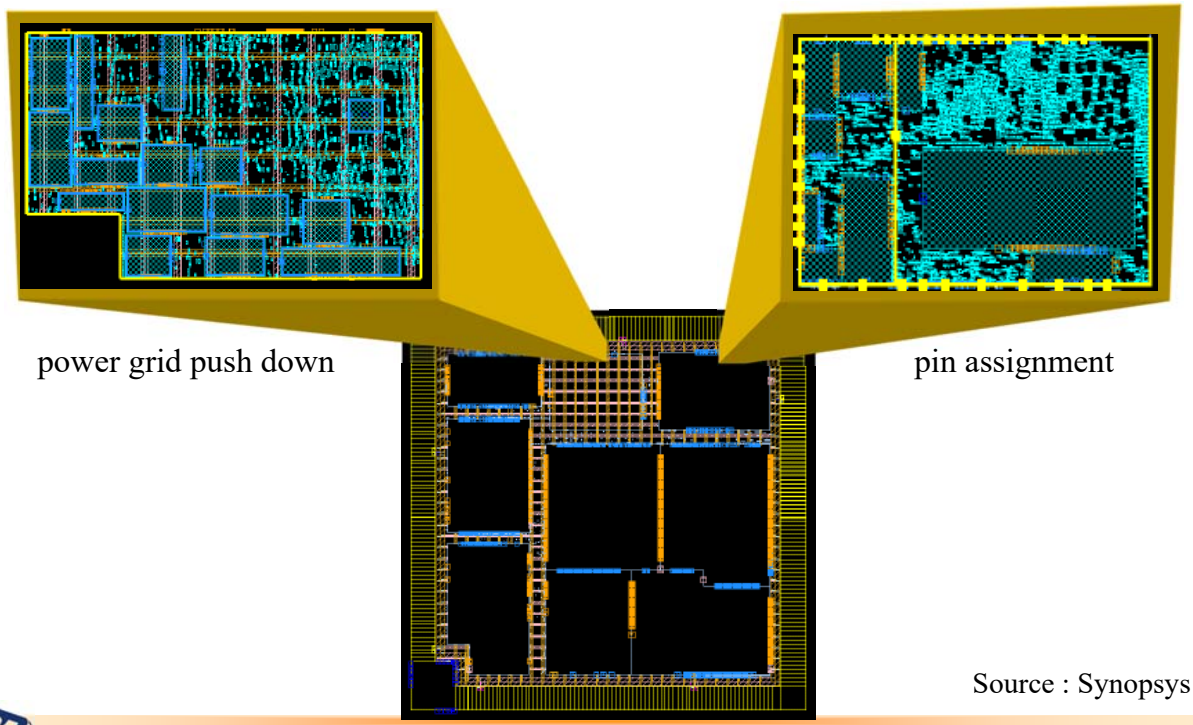
Physical Synthesis

- "Physical synthesis" is a new concept to solve timing closure problem at the synthesis step
- Integrate placement engine with logic synthesis to get more accurate wire length estimation
  - From outer loop to inner loop ??
- Not only database but also timing engine are integrated
  - Consistency makes better results



Hierarchical P&R

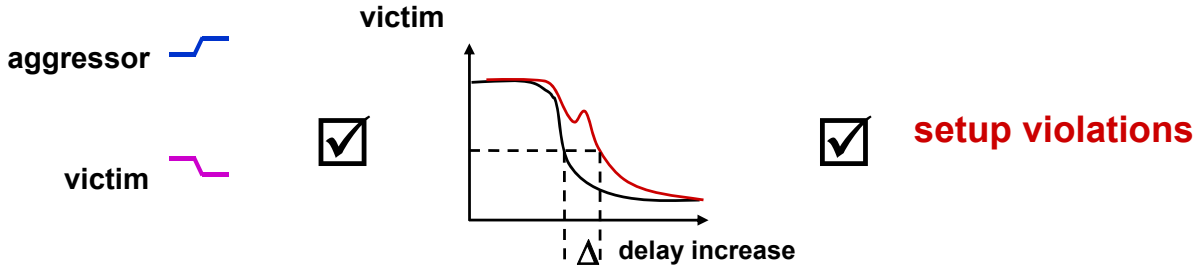
- Hierarchical methodologies are the key to cope high complexity !!



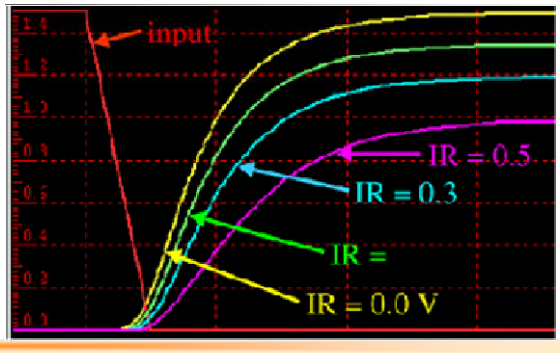
Source : Synopsys

Extra Checks for SI & IR-Drop

- Must be checked for signal integrity (SI) problems before manufacturing

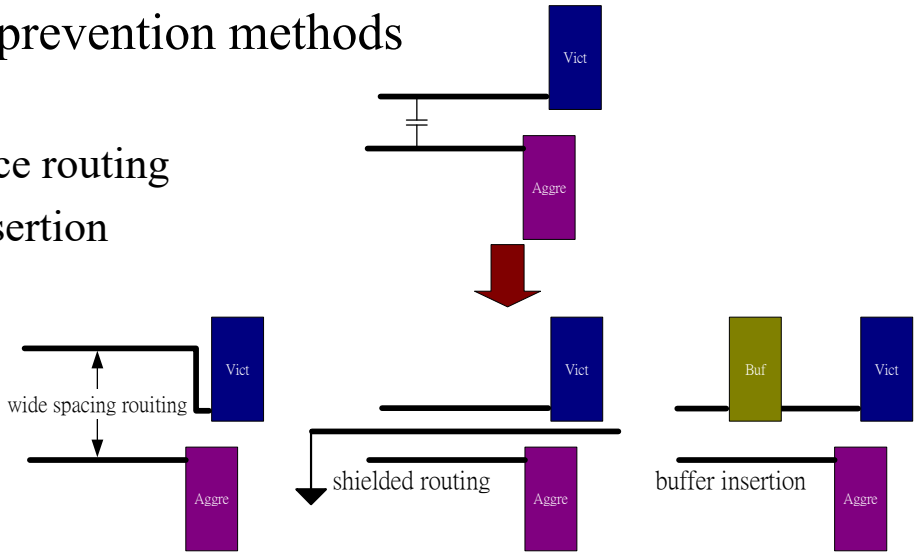


- IR-drop is also an serious problem due to large peak current



SI & IR-Drop Prevention

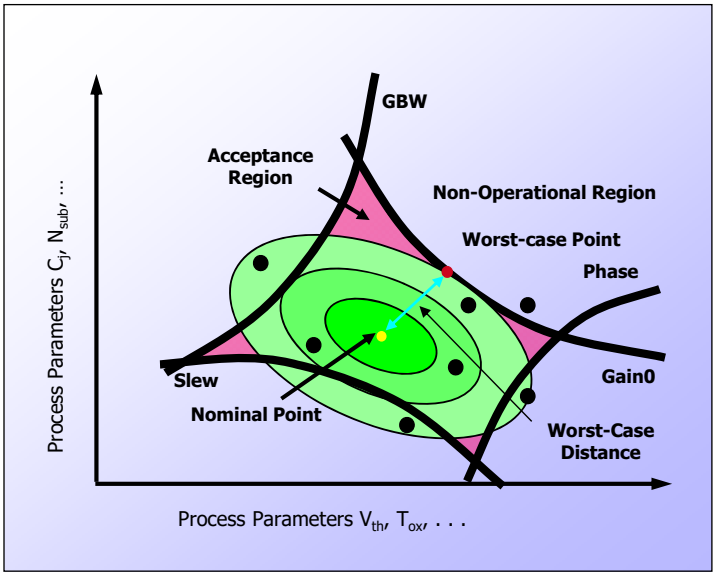
- Typical SI prevention methods
  - Shielding
  - Wide space routing
  - Buffer insertion



- To prevent IR-drop problem, we have to identify the ***current density*** problems with power analysis

Solve Reliability Problems

- There are still some problems that can make chip fail after a period of time
  - Electron migration
  - Hot electron
  - Process variation
  - ……
- Use design-for-manufacturing (DFM) or design-for-Yield (DFY) techniques to obtain suitable design margins



Source : ChipMD

Conclusions

工欲善其事
必先利其器 !!

- SoC is really a big challenge for IC designers
- Design methodology requires a big change
  - Reusing existing IPs and platforms is the key
- More powerful tools are essential to solve those difficult design problems
- ***EDA – Where Electronics Begins***